

• General Description

The ZMD68203TS combines advanced trench MOSFET technology with a low resistance package to provide extremely low $R_{DS(ON)}$. Two P Channel MOSFET inside for dual DIE implication.

• Features

- Advance high cell density Trench technology
- Low $R_{DS(ON)}$ to minimize conductive loss
- Low Gate Charge for fast switching
- Dual DIE in one package

• Application

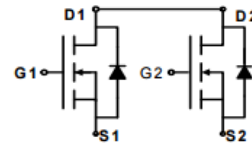
- Power Management
- Load Switch

• Ordering Information:

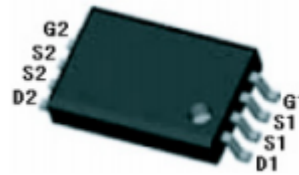
Part NO.	ZMD68203TS
Marking	ZMD68203T
Packing Information	REEL TAPE
Basic ordering unit (pcs)	4000

• P Channel Absolute Maximum Ratings ($T_C = 25^\circ\text{C}$)

Parameter	Symbol	Rating	Unit
Drain-Source Voltage	V_{DS}	20	V
Gate-Source Voltage	V_{GS}	± 12	V
Continuous Drain Current	$I_{D@TC=25^\circ\text{C}}$	14	A
	$I_{D@TC=75^\circ\text{C}}$	10.4	A
	$I_{D@TC=100^\circ\text{C}}$	8.8	A
Pulsed Drain Current ^①	I_{DM}	30	A
Total Power Dissipation($TC=25^\circ\text{C}$)	$P_D@TC=25^\circ\text{C}$	3.6	W
Total Power Dissipation($TA=25^\circ\text{C}$)	$P_D@TA=25^\circ\text{C}$	0.69	W
Operating Junction Temperature	T_J	-55 to 150	$^\circ\text{C}$
Storage Temperature	T_{STG}	-55 to 150	$^\circ\text{C}$
Single Pulse Avalanche Energy	E_{AS}	50	mJ

• Product Summary


$V_{DS1} = 20\text{V}$
 $V_{DS2} = 20\text{V}$
 $R_{DS(ON)1} = 8.5\text{m}\Omega$
 $R_{DS(ON)2} = 8.5\text{m}\Omega$
 $I_{D1} = 14\text{A}$
 $I_{D2} = 14\text{A}$


TSSOP-8

•Thermal resistance

Parameter	Symbol	Min.	Typ.	Max.	Unit
Thermal resistance, junction - case	R_{thJC}	-	-	34	$^{\circ}C/W$
Thermal resistance, junction - ambient	R_{thJA}	-	-	180	$^{\circ}C/W$
Soldering temperature, wavesoldering for 10s	T_{sold}	-	-	265	$^{\circ}C$

Electronic Characteristics

Parameter	Symbol	Condition	Min.	Typ	Max.	Unit
Drain-Source Breakdown Voltage	BV_{DSS}	$V_{GS}=0V, I_D=250\mu A$	20			V
Gate Threshold Voltage	$V_{GS(TH)}$	$V_{GS}=V_{DS}, I_D=250\mu A$	0.3		1	V
Drain-Source Leakage Current	I_{DSS}	$V_{DS}=20V, V_{GS}=0V$			1.0	μA
Gate- Source Leakage Current	I_{GSS}	$V_{GS}=\pm 12V, V_{DS}=0V$			± 100	nA
Static Drain-source On Resistance	$R_{DS(ON)}$	$V_{GS}=4.5V, I_D=14A$		8.5	10.5	$m\Omega$
		$V_{GS}=2.5V, I_D=10A$		10	12	$m\Omega$
Forward Transconductance	g_{FS}	$V_{DS}=10V, I_D=10A$		15		s
Source-drain voltage	V_{SD}	$I_S=14A$			1.28	V

•Electronic Characteristics

Parameter	Symbol	Condition	Min.	Typ	Max.	Unit
Input capacitance	C_{iss}	$f = 1MHz$	-	1050	-	pF
Output capacitance	C_{oss}		-	250	-	
Reverse transfer capacitance	C_{rss}		-	120	-	

•Gate Charge characteristics($T_a = 25^{\circ}C$)

Parameter	Symbol	Condition	Min.	Typ	Max.	Unit
Total gate charge	Q_g	$V_{DD}=25V$ $I_D=8A$ $V_{GS}=10V$	-	12	-	nC
Gate - Source charge	Q_{gs}		-	2	-	
Gate - Drain charge	Q_{gd}		-	5	-	

•P Channel characteristics curve

Fig.1 Power Dissipation Derating Curve

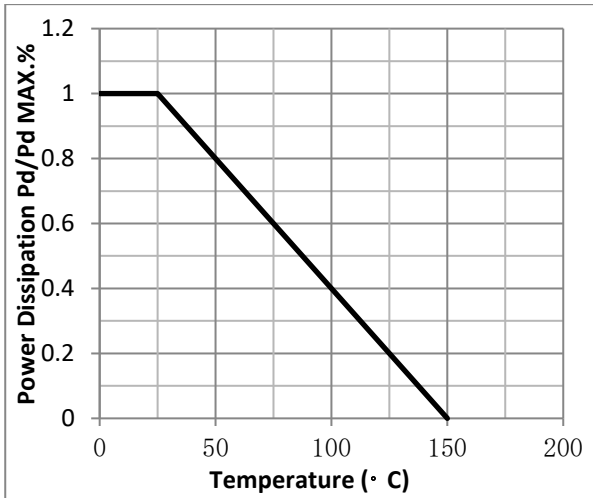


Fig.2 Typical output Characteristics

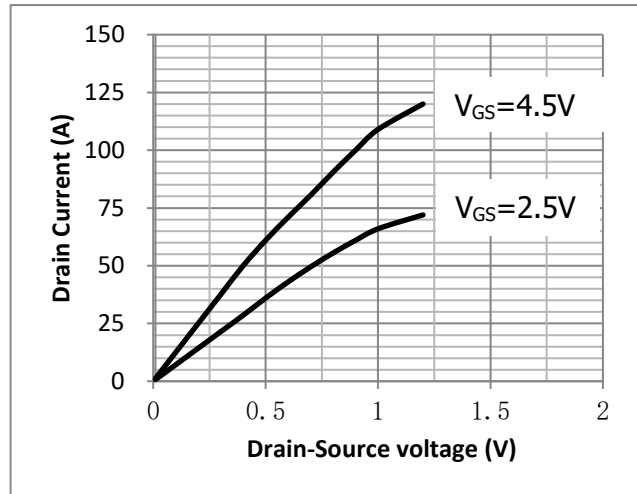


Fig.3 Threshold Voltage V.S Junction Temperature

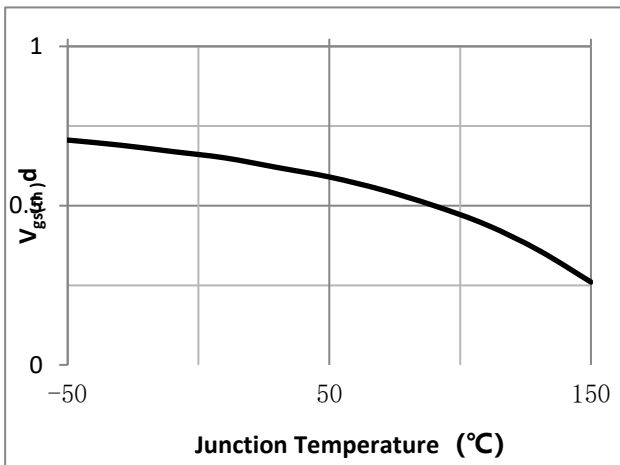


Fig.4 Resistance V.S Drain Current

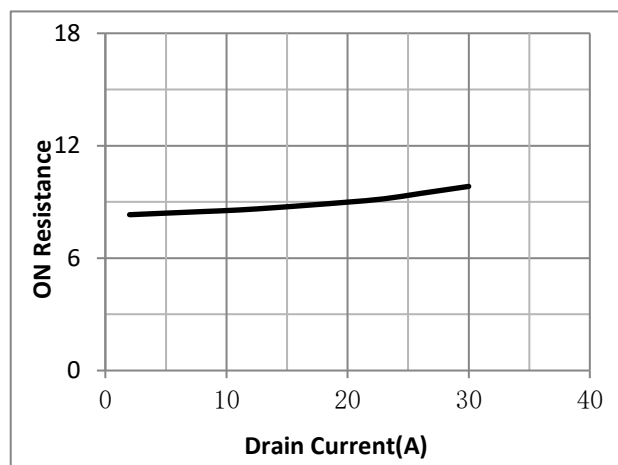


Fig.5 On-Resistance VS Gate Source Voltage

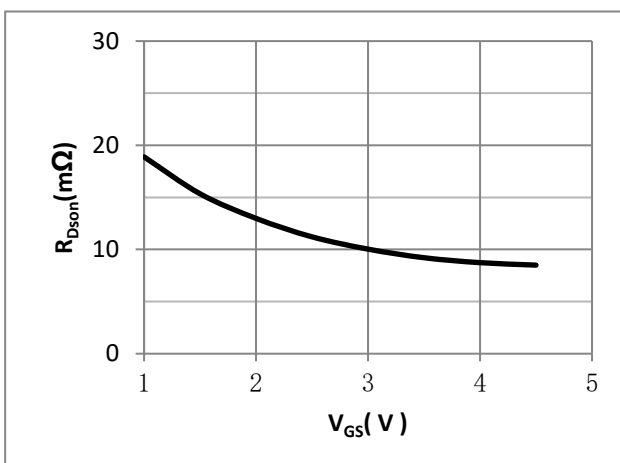
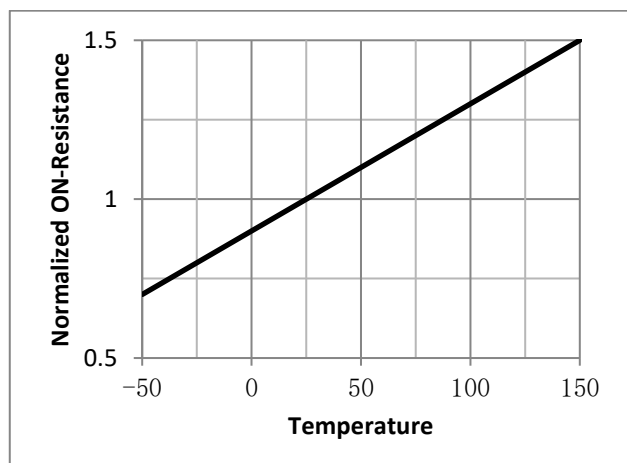


Fig.6 On-Resistance V.S Junction Temperature



• Test Circuit

Fig.1 Switching Time Measurement Circuit

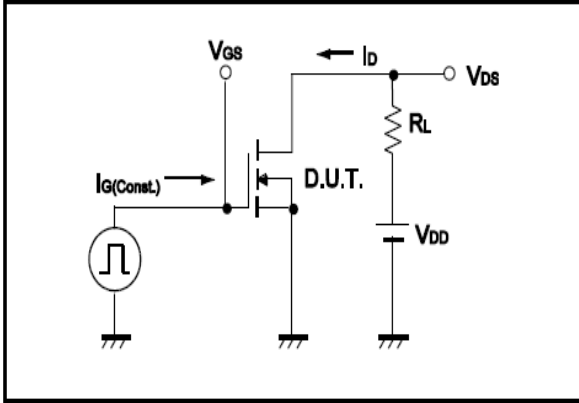


Fig.2 Gate Charge Waveform

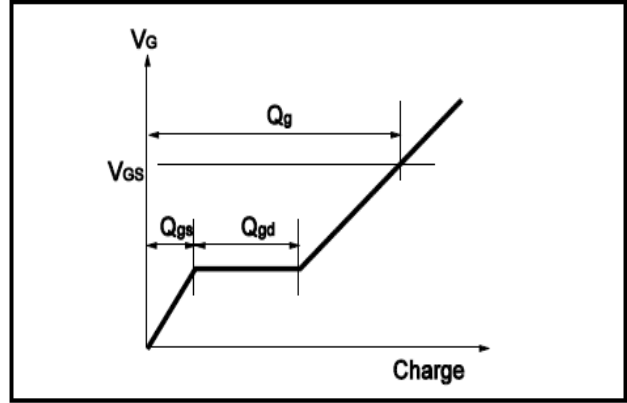


Fig.3 Switching Time Measurement Circuit

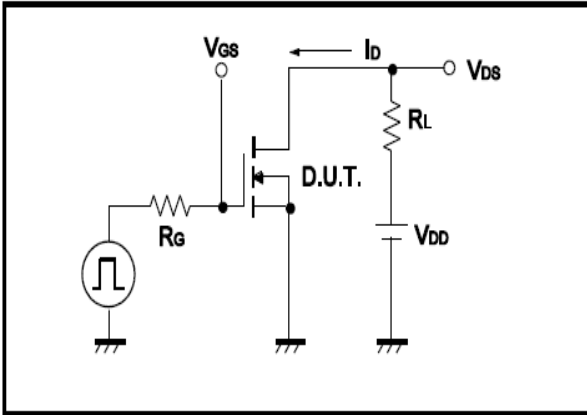


Fig.4 Gate Charge Waveform

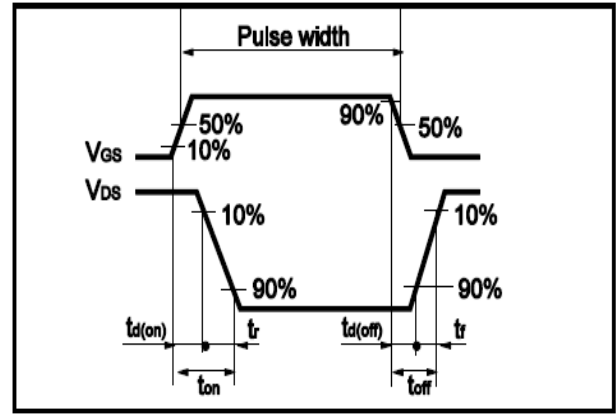


Fig.5 Avalanche Measurement Circuit

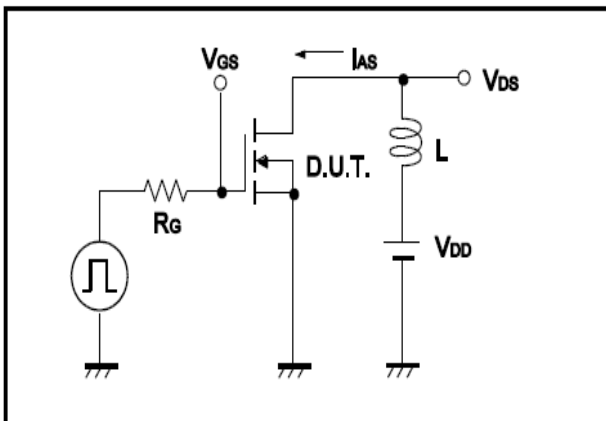
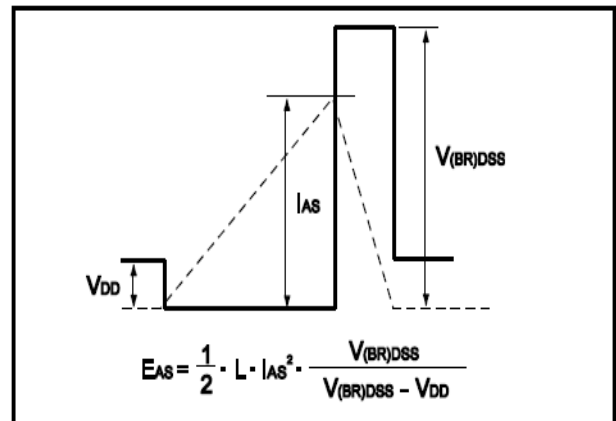


Fig.6 Avalanche Waveform



•Dimensions(TSSOP-8)

Unit: mm

Symbol	Dimensions In Millimeters	
	Min	Max
D	2.900	3.100
E	4.300	4.500
b	0.190	0.300
c	0.090	0.200
E1	6.250	6.550
A		1.100
A2	0.800	1.000
A1	0.020	0.150
e	0.65(BSC)	
L	0.500	0.700
H	0.25(TYP)	
Θ	1°	7°

